

METHOD AND SYSTEM FOR
REDUCING THICKNESS OF SPIN-ON GLASS ON
SEMICONDUCTOR WAFERS

5

ABSTRACT OF THE DISCLOSURE

10

A method for reducing thickness of spin-on glass on semiconductor wafers includes rotatably mounting a semiconductor wafer and positioning a grinding member proximate an outer edge of the semiconductor wafer. The method further includes rotating both the semiconductor wafer and the grinding member, and engaging the rotating grinding member with the outer edge of the rotating semiconductor wafer while applying a chemical to the outer edge.

TI-29038 (032350.B207)